



Material Content Data Sheet



Sales Product Name		TLD5541-2QV		Issued		1. August 2018		
MA#		MA001710522						
Package		PG-VQFN-48-31		Weight*		129.47 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.470	1.91	1.91	19077	19077
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		553	
	non noble metal	iron	7439-89-6	1.433	1.11		11070	
wire	non noble metal	copper	7440-50-8	58.193	44.94	46.12	449476	461237
	non noble metal	copper	7440-50-8	0.651	0.50	0.50	5029	5029
	organic material	carbon black	1333-86-4	0.188	0.15		1451	
encapsulation	plastics	epoxy resin	-	7.955	6.14		61444	
	inorganic material	silicondioxide	60676-86-0	54.496	42.09	48.38	420918	483813
leadfinish	non noble metal	tin	7440-31-5	2.596	2.01	2.01	20054	20054
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4741	4741
glue	plastics	epoxy resin	-	0.180	0.14		1391	
	noble metal	silver	7440-22-4	0.603	0.47	0.61	4658	6049
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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